PC3H41x NIP Series
PC3Q410 NIP

AC Input, Low Input Current Type Photocoupler

■ Features

1. Low input current type (I_F=±0.5mA)
2. High resistance to noise due to high common rejection voltage (CMR:MIN. 10kV/μs)
3. AC input type
4. Mini-flat package **PC3H41x NIP Series** (1ch)
   PC3Q410 NIP (4ch)
5. Isolation voltage (Viso:2.5kVrms)
6. Recognized by UL, file No. E64380

■ Applications

1. Programmable controllers
2. Facsimiles
3. Telephones

■ Rank Table

Model No.	Rank mark	Ic (mA)	Conditions
PC3H410NIP	A or no mark	0.25 to 2.0	I_F=±0.5mA V_{CE}=5V T_a=25°C
PC3H411NIP	A	0.5 to 1.5	

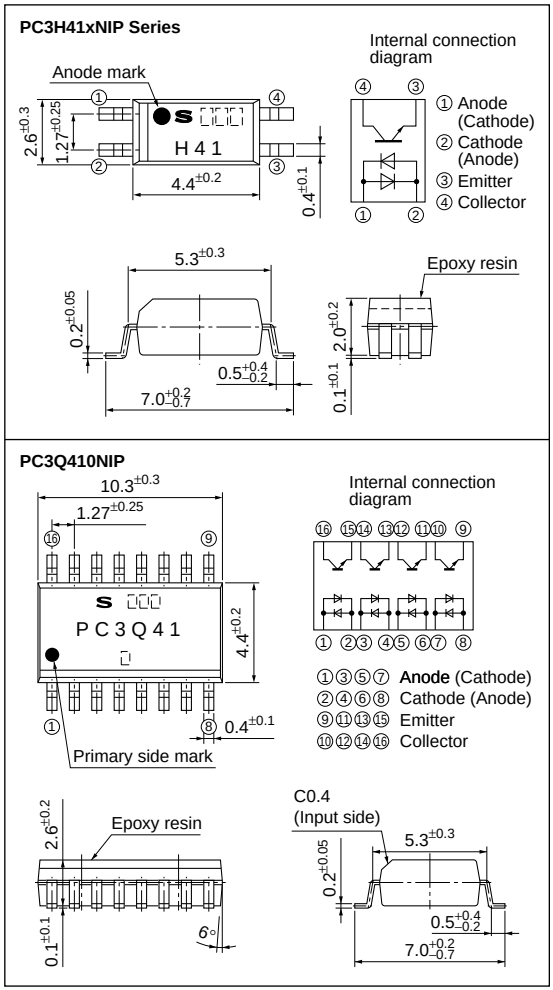
Model No.	Rank mark	Ic (mA)	Conditions
PC3Q410NIP	No mark	0.25 to 2.0	I_F=±0.5mA V_{CE}=5V T_a=25°C

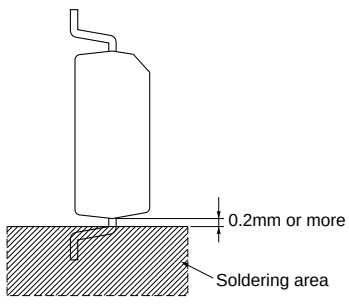
■ Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	±10	mA
	*1 Peak forward current	I_{FM}	±200	mA
	Power dissipation	P	15	mW
Output	Collector-emitter voltage	V_{CEO}	70	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_C	50	mA
	Collector power dissipation	P_C	150	mW
Total power dissipation		P_{tot}	170	mW
Operating temperature		T_{opr}	–30 to +100	°C
Storage temperature		T_{stg}	–40 to +125	°C
*2 Isolation voltage		V_{iso}	2.5	kV_{rms}
*3 Soldering temperature		T_{sol}	260	°C

*1 Pulse width<=100μs, Duty ratio=0.001
*2 40 to 60%RH, AC for 1 minute, f=60Hz
*3 For 10s

■ Outline Dimensions (Unit : mm)





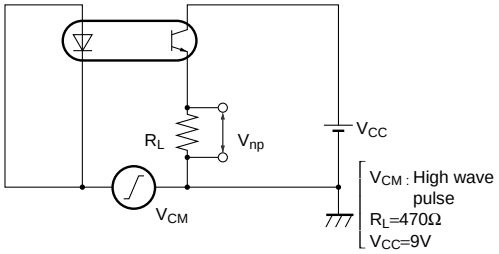
■ Electro-optical Characteristics

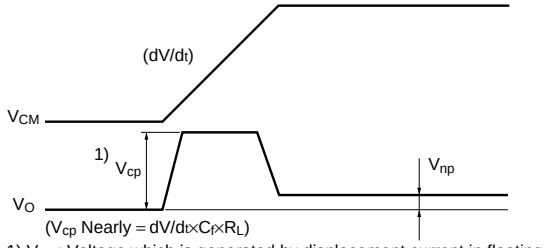
(Ta=25°C)

	Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		V_F	I_F=±10mA	–	1.2	1.4	V
	Terminal capacitance		C_t	V=0, f=1kHz	–	30	250	pF
Output	Collector dark current		I_{CEO}	V_{CE}=50V, I_F=0	–	–	100	nA
	Collector-emitter breakdown voltage		BV_{CEO}	I_C=0.1mA, I_F=0	70	–	–	V
	Emitter-collector breakdown voltage		BV_{ECO}	I_E=10μA, I_F=0	6	–	–	V
Transfer characteristics	Collector current		I_C	I_F=±0.5mA, V_{CE}=5V	0.25	–	2.0	mA
	Collector-emitter saturation voltage		$V_{CE\ (sat)}$	I_F=±10mA, I_C=1mA	–	–	0.2	V
	Isolation resistance		R_{ISO}	DC500V 40 to 60%RH	5×10^{10}	10^{11}	–	Ω
	Floating capacitance		C_f	V=0, f=1MHz	–	0.6	1.0	pF
	Response time	Rise time	tr	V_{CE}=2V, I_C=2mA, R_L=100Ω	–	4	18	μs
		Fall time	tf		–	3	18	μs
	*1 Common mode rejection voltage		CMR	Ta=25°C, R_L=470Ω, V_{CM}=1.5kV (peak), I_F=0mA, V_{CC}=9V, Vnp=100mV	10	–	–	kV/μs

*1 Refer to Fig.1.

Fig.1 Test Circuit for Common Mode Rejection Voltage





1) V_{cp} : Voltage which is generated by displacement current in floating capacitance between primary and secondary side.

Fig.2 Forward Current vs. Ambient Temperature

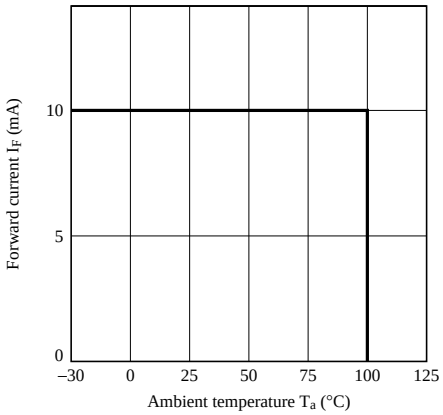


Fig.3 Diode Power Dissipation vs. Ambient Temperature

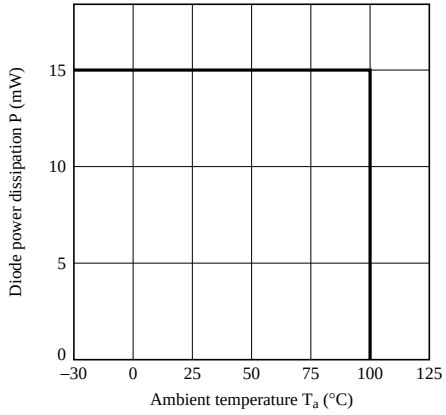


Fig.4 Collector Power Dissipation vs. Ambient Temperature

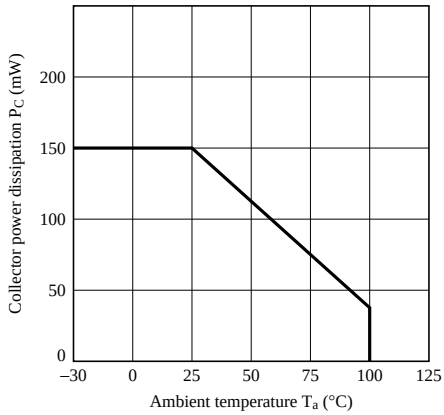


Fig.5 Total Power Dissipation vs. Ambient Temperature

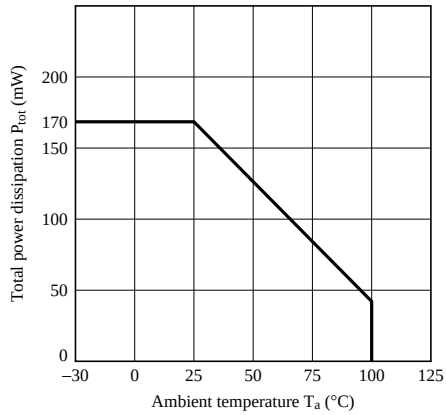


Fig.6 Peak Forward Current vs. Duty Ratio

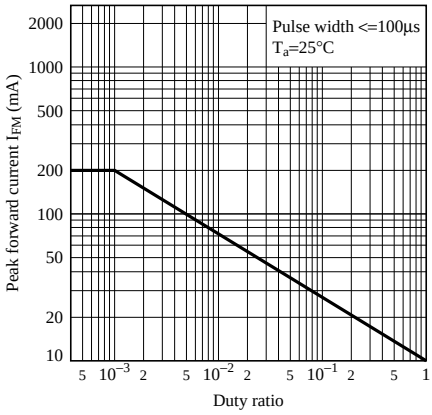


Fig.7 Forward Current vs. Forward Voltage

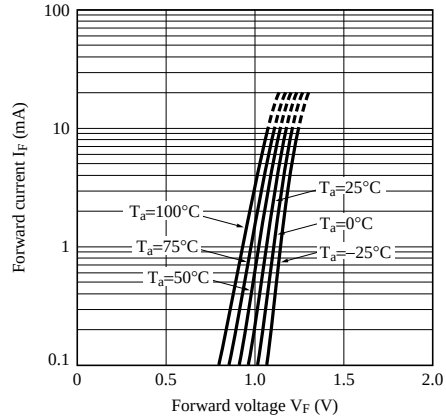


Fig.8 Current Transfer Ratio vs. Forward Current

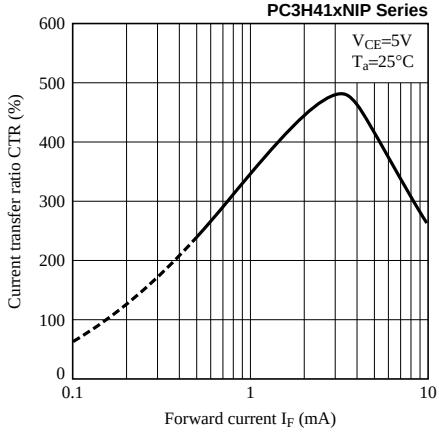


Fig.9 Current Transfer Ratio vs. Forward Current

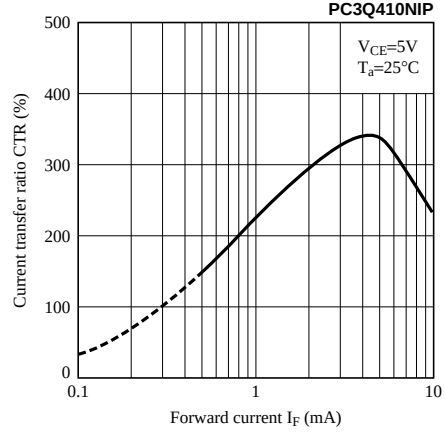


Fig.10 Collector Current vs. Collector-emitter Voltage

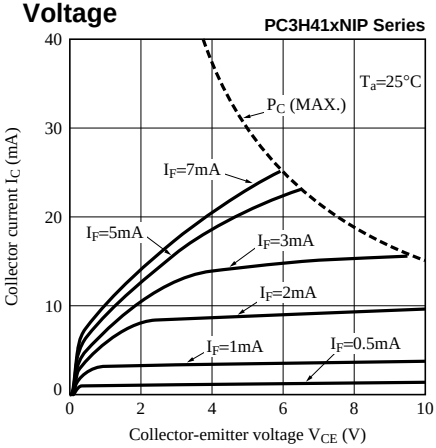


Fig.11 Collector Current vs. Collector-emitter Voltage

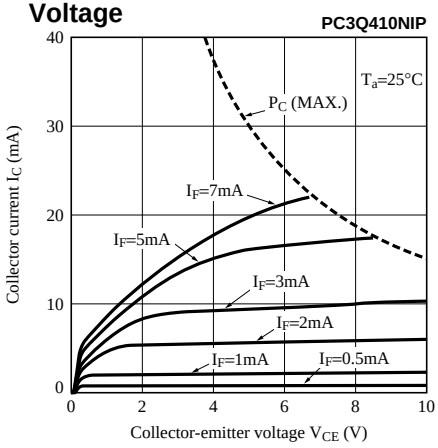


Fig.12 Relative Current Transfer Ratio vs. Ambient Temperature

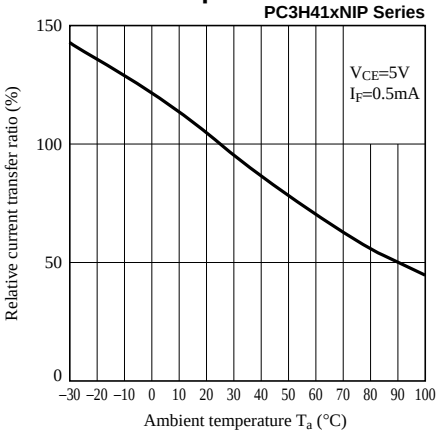


Fig.13 Relative Current Transfer Ratio vs. Ambient Temperature

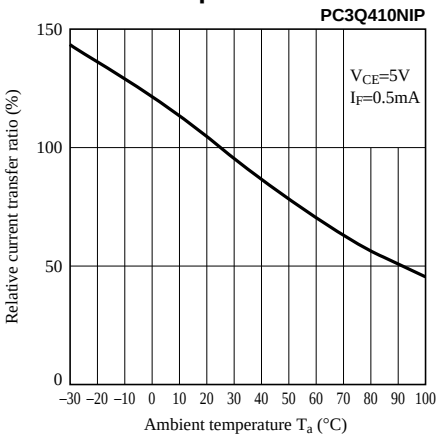


Fig.14 Collector - emitter Saturation Voltage vs. Ambient Temperature

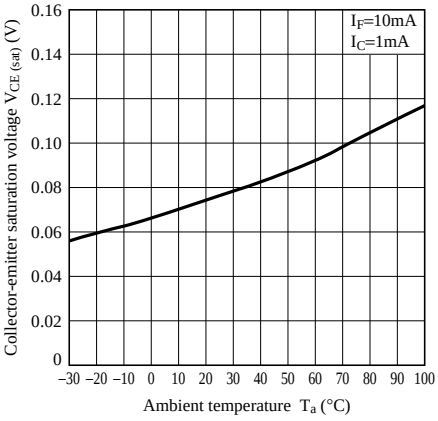


Fig.15 Collector Dark Current vs. Ambient Temperature

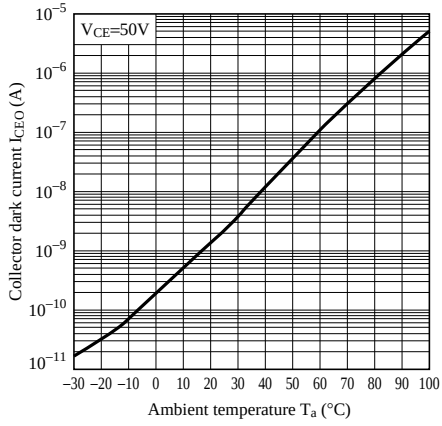


Fig.16 Response Time vs. Load Resistance

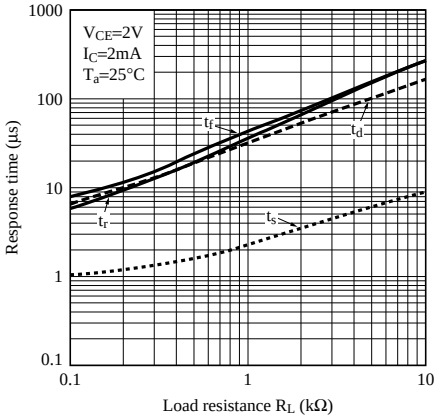


Fig.17 Response Time vs. Load Resistance (Saturation)

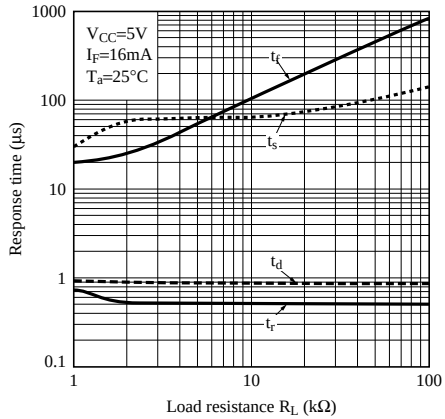


Fig.18 Test Circuit for Response Time

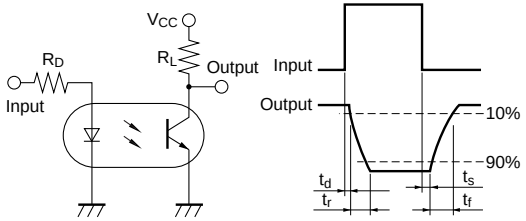


Fig.19 Voltage Gain vs Frequency

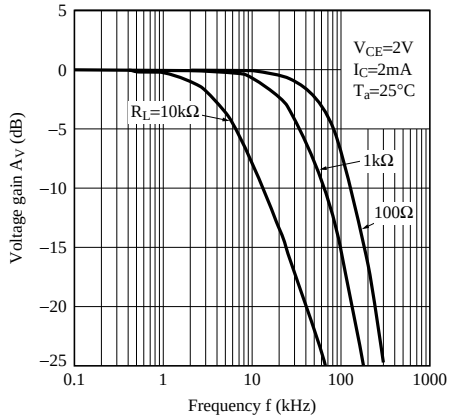


Fig.20 Collector-emitter Saturation Voltage vs. Forward Current

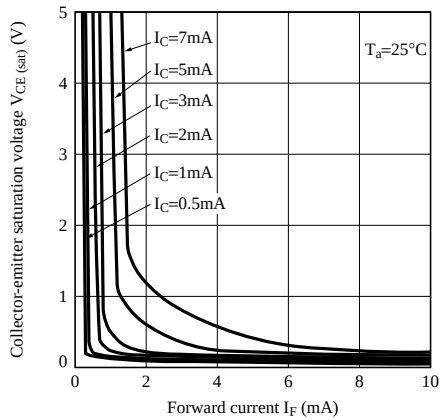
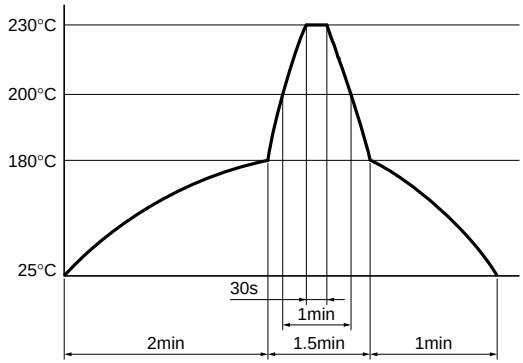


Fig.21 Reflow Soldering

Only one time soldering is recommended within the temperature profile shown below.



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